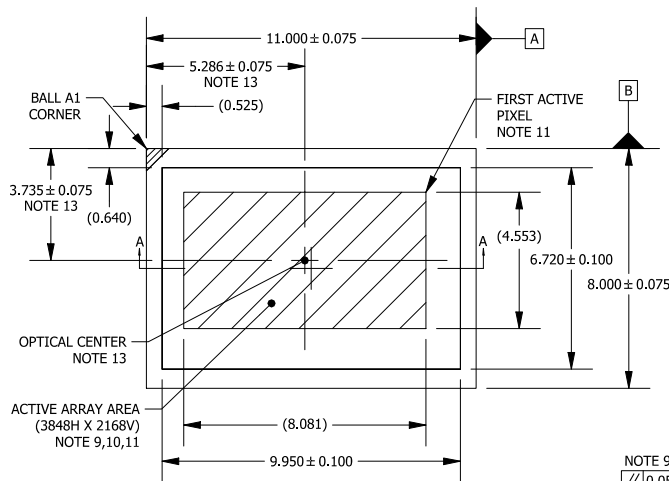
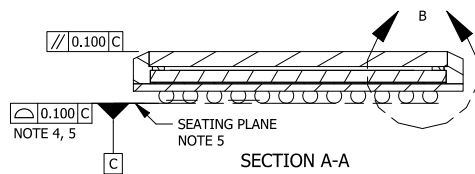


IBGA95 11x8
CASE 503BW
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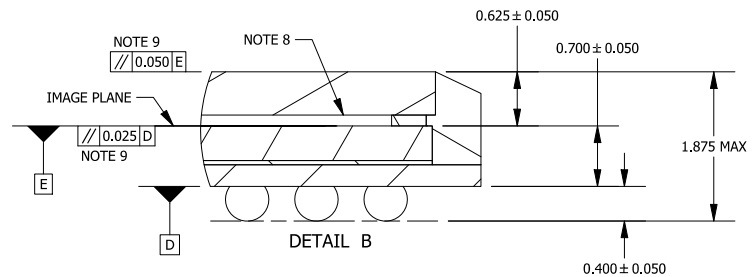
DATE 24 MAR 2021



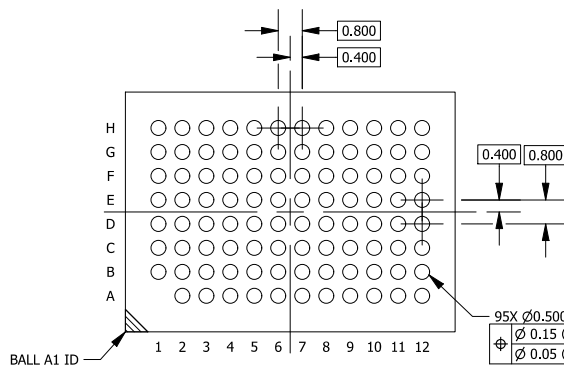
TOP VIEW



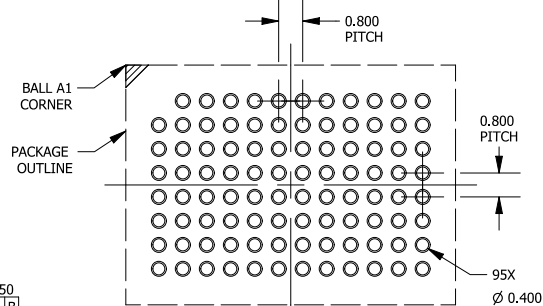
SECTION A-A



DETAIL B



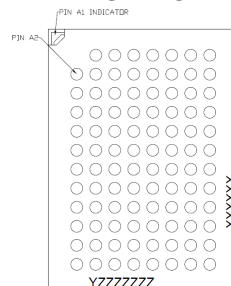
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

***FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.**

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

Y = Year

ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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